

15.58/6459

#10/B

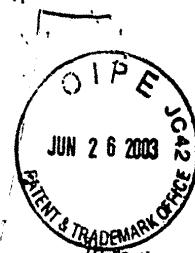
Marsha
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JUN 30 2003

TECHNOLOGY CENTER 2800

Group Art Unit: 2818
Examiner: Ho, Tu Tu V.



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Re the Application of
Tomoyuki FURUHATA
Serial No.: 10/053,910
Filing Date: January 24, 2002
For: SEMICONDUCTOR DEVICES AND
METHODS FOR MANUFACTURING
THE SAME

AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sirs:

In response to the Office Action dated March 21, 2003, the response being due by Monday, June 23, 2003 (June 21 was a Saturday), please enter and consider the following.

Please enter the following claim set:

1-25. (canceled)

B1

1 ~~26.~~ (new) A semiconductor device including a semiconductor substrate, comprising:
a protective insulation layer;
a pad opening section provided in the protective insulation layer;
an upper wiring layer which the pad opening section reaches, the upper wiring layer
including first and second sub-layers electrically connected to each other, the second sub-layer
including an upper surface that is contacted by the pad opening section;
a insulating layer positioned between end regions of the first and second sub-layers; and
an additional wiring layer provided at a level lower than the wiring layer which the pad
opening section reaches;

72.00 op
168.00 op

06/27/2003 SSESHE1 00000020 0053910
01 FC:1202
02 FC:1201